

IN THE SPECIFICATION

Please amend the following paragraph as follows:

[0069] Assemblies in accordance with embodiments of the present invention may be formed as discussed in certain embodiments of U.S. Patent 5,518,964, the disclosure of which is hereby incorporated by reference herein. Such assemblies may incorporate certain features taught in certain embodiments of U.S. Patents 5,798,286, 5,830,782, and 5,688,716, the disclosures of which are hereby incorporated by reference herein. Assemblies in accordance with certain embodiments of the present invention may also incorporate features disclosed in certain embodiments of U.S. Patent 5,913,109 and U.S. Patent Application Serial No. 09/271,688, filed March 18, 1999, now U.S. Patent 6,429,112, the disclosures of which are hereby incorporated by reference herein.